HLMP-3301, HLMP-3401, HLMP-3507, HLMP-3762, HLMP-3862, HLMP-3962, HLMP-D401



T-1³/₄ (5 mm) Diffused LED Lamps

Data Sheet



Description

This family of T-1³/₄ tinted, diffused LED lamps is widely used in general purpose indicator applications. Diffusants, tints, and optical design are balanced to yield superior light output and wide viewing angles. Several intensity choices are available in each color for increased design flexibility.

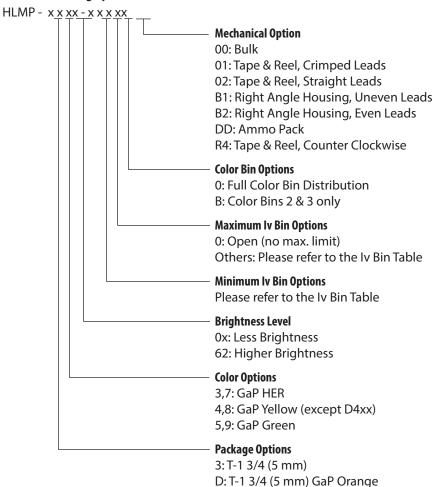
Selection Guide

Material/			us Intensity at 10 mA
Color	Part Number	Min.	Max.
	HLMP-3301	5.4	-
	HLMP-3301-D00xx	2.1	-
GaP HER	HLMP-3301-F00xx	5.4	-
	HLMP-3301-FG0xx	5.4	17.2
	HLMP-3762	8.6	-
	HLMP-3762-G00xx	8.6	-
	HLMP-3401	5.7	-
GaP Yellow	HLMP-3401-E00xx	5.7	-
	HLMP-3401-EF0xx	5.7	18.4
	HLMP-3862	9.2	-
GaP Orange	HLMP-D401	5.4	-
	HLMP-D401-EF0xx	3.4	10.8
	HLMP-3507	4.2	-
	HLMP-3507-D00xx	4.2	-
GaP Green	HLMP-3507-EF0xx	6.7	21.2
	HLMP-3962	10.6	-
	HLMP-3962-F00xx	10.6	-

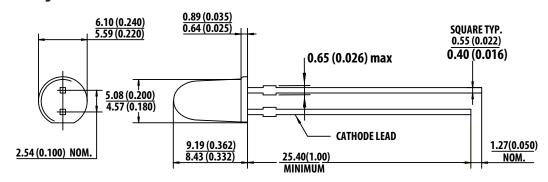
Features

- High intensity
- Choice of 4 bright colors
 - High Efficiency Red
 - Orange
 - Yellow
 - High Performance Green
- Popular T-1³/₄ diameter package
- Selected minimum intensities
- Wide viewing angle
- General purpose leads
- Reliable and rugged
- Available on tape and reel

Part Numbering System



Package Dimensions



Notes:

- 1. All dimensions are in mm (inches).
- 2. An epoxy meniscus may extend about 1 mm (0.040") down the leads.
- 3. For PCB hole recommendations, see the Precautions section.

Optical/Electrical Characteristics at $T_A = 25^{\circ}C$

Symbol	Parameter	Color	Min.	Тур.	Max.	Units	Test Condition
$\frac{3911001}{20^{1}/2}$	Included Angle	High Efficiency Red	1411114	60	Max.	Deg.	I _F = 10 mA
20 72	Between Half	Orange		60		z cg.	See Note 1
	Luminous Intensity	Yellow		60			occinote i
	Points	Green		60			
λρεακ	Peak Wavelength	High Efficiency Red		635		nm	Measurement
	_	Orange		600			at Peak
		Yellow		583			
		Green		565			
$\Delta\lambda_{1/2}$	Spectral Line Halfwidth	HER/Orange		40		nm	
		Yellow		36			
		Green		28			
λ_d	Dominant Wavelength	High Efficiency Red		626		nm	See Note 2
		Orange		602			
		Yellow		585			
		Green		569			
τ_{s}	Speed of Response	High Efficiency Red		90		ns	
		Orange		280			
		Yellow		90			
		Green		500			
C	Capacitance	High Efficiency Red		11		pF	$V_F = 0;$
		Orange		4			f = 1 MHz
		Yellow		15			
		Green		18			
$R\theta_{J\text{-PIN}}$	Thermal Resistance	All		260		°C/W	Junction to
							Cathode Lead
V_{F}	Forward Voltage	HER/Orange		1.9	2.4	V	$I_F = 10 \text{ mA}$
		Yellow		2.0	2.4		
		Green		2.1	2.7		
V_R	Reverse Breakdown Voltage	All	5.0			V	$I_R = 100 \mu A$
ηγ	Luminous Efficacy	High Efficiency Red	-	145		lumens	See Note 3
		Orange		380		Watt	
		Yellow	-	500			
		Green		595			

Notes:

- $1.\,\theta^{1}/_{2}$ is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 2. The dominant wavelength, λ_{dr} is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
- 3. Radiant intensity, I_e , in Watts/steradian, may be found from the equation $I_e = I_V/\eta_V$, where I_V is the luminous intensity in candelas and η_V is the luminous efficacy in lumens/Watt.

Absolute Maximum Ratings at T_A = 25°C

			Green/	
Parameter	HER/Orange	Yellow	Emerald Green	Units
Peak Forward Current	90	60	90	mA
Average Forward Current ^[1]	25	20	25	mA
DC Current ^[2]	30	20	30	mA
Power Dissipation ^[3]	135	85	135	mW
Reverse Voltage (I _R = 100 μA)	5	5	5	V
Transient Forward Current ^[4] (10 µsec Pulse)	500	500	500	mA
LED Junction Temperature	110	110	110	°C
Operating Temperature Range	-40 to +100	-40 to +100	-20 to +100	°C
Storage Temperature Range	-40 to +100	-40 to +100	-40 to +100	°C

Notes:

- 1. See Figure 5 (Red/Orange), 10 (Yellow), or 15 (Green) to establish pulsed operating conditions.
- 2. For Red, Orange and Green series derate linearly from 50°C at 0.5 mA/°C. For Yellow series derate linearly from 50°C at 0.2 mA/°C.
- 3. 1.8 mW/°C. For Yellow series derate power linearly from 50°C at 1.6 mW/°C.
- 4. The transient peak current is the maximum non-recurring peak current that can be applied to the device without damaging the LED die and wirebond. It is not recommended that the device be operated at peak currents beyond the peak forward current listed in the Absolute Maximum Ratings.

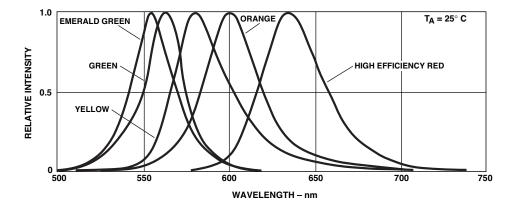


Figure 1. Relative intensity vs. wavelength

T-1³/₄ High Efficiency Red, Orange Diffused Lamps

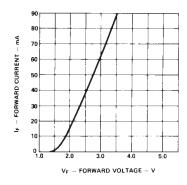


Figure 2. Forward current vs. forward voltage characteristics

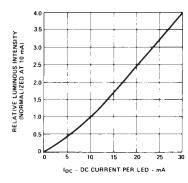


Figure 3. Relative luminous intensity vs. DC forward current

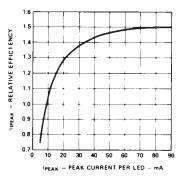


Figure 4. Relative efficiency (luminous intensity per unit current) vs. peak LED current

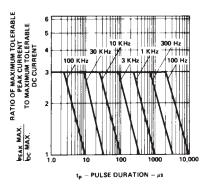


Figure 5. Maximum tolerable peak current vs. pulse duration. (I_{DC} MAX as per MAX ratings)

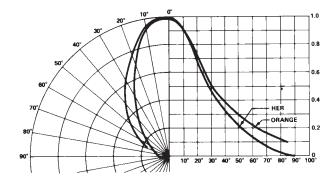


Figure 6. Relative luminous intensity vs. angular displacement

T-1³/₄ Yellow Diffused Lamps

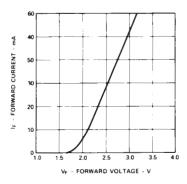


Figure 7. Forward current vs. forward voltage characteristics

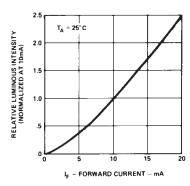


Figure 8. Relative luminous intensity vs. forward current

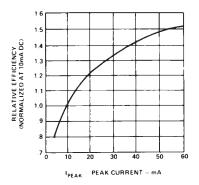


Figure 9. Relative efficiency (luminous intensity per unit current) vs. peak current

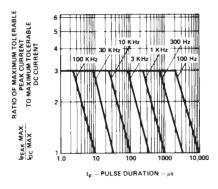


Figure 10. Maximum tolerable peak current vs. pulse duration. (I_{DC} MAX as per MAX ratings)

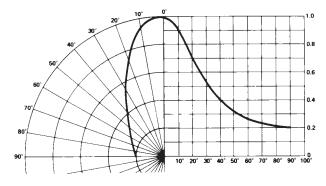


Figure 11. Relative luminous intensity vs. angular displacement

T-1³/₄ Green/Emerald Green Diffused Lamps

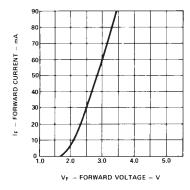


Figure 12. Forward current vs. forward voltage characteristics

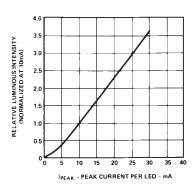


Figure 13. Relative luminous intensity vs. DC forward current

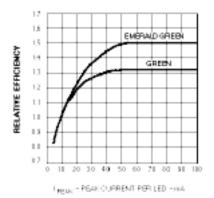


Figure 14. Relative efficiency (luminous intensity per unit current) vs. peak LED current

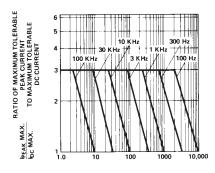


Figure 15. Maximum tolerable peak current vs. pulse duration. (I_{DC} MAX as per MAX ratings)

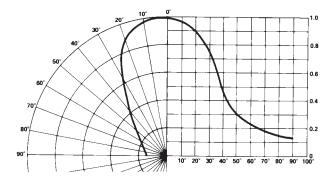


Figure 16. Relative luminous intensity vs. angular displacement

Intensity Bin Limits

Color Bin Min. D 2.4 E 3.8 F 6.1 G 9.7 H 15.5 I 24.8 J 39.6 K 63.4 L 101.5	Max. 3.8 6.1 9.7 15.5 24.8 39.6 63.4
E 3.8 F 6.1 G 9.7 H 15.5 I 24.8 J 39.6 K 63.4	6.1 9.7 15.5 24.8 39.6 63.4
F 6.1 G 9.7 H 15.5 I 24.8 J 39.6 K 63.4	9.7 15.5 24.8 39.6 63.4
G 9.7 H 15.5 I 24.8 J 39.6 K 63.4	15.5 24.8 39.6 63.4
H 15.5 I 24.8 J 39.6 K 63.4	24.8 39.6 63.4
I 24.8 J 39.6 K 63.4	39.6 63.4
J 39.6 K 63.4	63.4
K 63.4	
L 101.5	101.5
	162.4
M 162.4	234.6
N 234.6	340.0
Red/Orange O 340.0	540.0
P 540.0	850.0
Q 850.0	1200.0
R 1200.0	1700.0
S 1700.0	2400.0
T 2400.0	3400.0
U 3400.0	4900.0
V 4900.0	7100.0
W 7100.0	10200.0
X 10200.0	14800.0
Y 14800.0	21400.0
Z 21400.0	30900.0
E 6.5	10.3
F 10.3	16.6
G 16.6	26.5
H 26.5	42.3
1 42.3	67.7
J 67.7	108.2
K 108.2	173.2
L 173.2	250.0
M 250.0	360.0
/ellow N 360.0	510.0
O 510.0	800.0
P 800.0	1250.0
Q 1250.0	1800.0
R 1800.0	2900.0
S 2900.0	4700.0
T 4700.0	7200.0
U 7200.0	11700.0
V 11700.0	18000.0
	27000.0
W 18000.0	27000 0

Intensity Bin Limits, continued

		Intensity Range	(mcd)
Color	Bin	Min.	Max.
	D	4.7	7.6
	E	7.6	12.0
	F	12.0	19.1
	G	19.1	30.7
	Н	30.7	49.1
	T	49.1	78.5
	J	78.5	125.7
	K	125.7	201.1
	L	201.1	289.0
Green	M	289.0	417.0
	N	417.0	680.0
	0	680.0	1100.0
	Р	1100.0	1800.0
	Q	1800.0	2700.0
	R	2700.0	4300.0
	S	4300.0	6800.0
	T	6800.0	10800.0
	U	10800.0	16000.0
	V	16000.0	25000.0
	W	25000.0	40000.0

Maximum tolerance for each bin limit is $\pm 18\%$.

Color Categories

		Lambda (nm)	
Color	Category #	Min.	Max.
	6	561.5	564.5
	5	564.5	567.5
Green	4	567.5	570.5
	3	570.5	573.5
	2	573.5	576.5
	1	582.0	584.5
	3	584.5	587.0
Yellow	2	587.0	589.5
	4	589.5	592.0
	5	592.0	593.0
	1	597.0	599.5
	2	599.5	602.0
	3	602.0	604.5
Orange	4	604.5	607.5
	5	607.5	610.5
	6	610.5	613.5
	7	613.5	616.5
	8	616.5	619.5

Tolerance for each bin limit is ± 0.5 nm.

Mechanical Option Matrix

Mechanical Option Code Definition		
00	Bulk Packaging, minimum increment 500 pcs/bag	
01	Tape & Reel, crimped leads, minimum increment 1300 pcs/bag	
02	Tape & Reel, straight leads, minimum increment 1300 pcs/bag	
B1	Right Angle Housing, uneven leads, minimum increment 500 pcs/bag	
B2	Right Angle Housing, even leads, minimum increment 500 pcs/bag	
DD	Ammo Pack, straight leads with minimum increment 2K/pack	
R4	Tape & Reel, straight leads, counter clockwise, anode lead leaving the reel first	

Note:

All categories are established for classification of products. Products may not be available in all categories. Please contact your local Avago representative for further clarification/information.

Precautions

Lead Forming

- The leads of an LED lamp may be preformed or cut to length prior to insertion and soldering into PC board.
- If lead forming is required before soldering, care must be taken to avoid any excessive mechanical stress induced to LED package. Otherwise, cut the leads of LED to length after soldering process at room temperature. The solder joint formed will absorb the mechanical stress of the lead cutting from traveling to the LED chip die attach and wirebond.
- It is recommended that tooling made to precisely form and cut the leads to length rather than rely upon hand operation.

Soldering Conditions

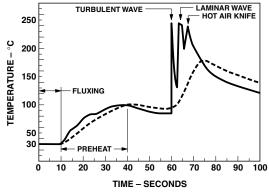
- Care must be taken during PCB assembly and soldering process to prevent damage to LED component.
- The closest LED is allowed to solder on board is 1.59 mm below the body (encapsulant epoxy) for those parts without standoff.
- Recommended soldering conditions:

		Manual Solder
	Wave Soldering	Dipping
Pre-heat Temperature	105 °C Max.	-
Pre-heat Time	30 sec Max.	-
Peak Temperature	250 °C Max.	260 °C Max.
Dwell Time	3 sec Max.	5 sec Max.

- Wave soldering parameter must be set and maintained according to recommended temperature and dwell time in the solder wave. Customer is advised to periodically check on the soldering profile to ensure the soldering profile used is always conforming to recommended soldering condition.
- If necessary, use fixture to hold the LED component in proper orientation with respect to the PCB during soldering process.
- Proper handling is imperative to avoid excessive thermal stresses to LED components when heated. Therefore, the soldered PCB must be allowed to cool to room temperature, 25°C, before handling.
- Special attention must be given to board fabrication, solder masking, surface plating and lead holes size and component orientation to assure solderability.
- Recommended PC board plated through hole sizes for LED component leads:

LED Component Lead Size Diagor Lead Size 0.45 × 0.45 mm (0.018 × 0.018 in.) 0.636 (0.025 mm) Dambar shear- off area (max.) 0.65 mm (0.036 in) 0.919 (0.036 in) Lead size (typ.) 0.50 × 0.50 mm (0.020 × 0.020 in.) 0.707 in (0.028 in) Dambar shear- off area (max.) 0.70 mm (0.028 in) 0.99 m	
(0.018 × 0.018 in.) (0.025 Dambar shear- 0.65 mm 0.919 off area (max.) (0.026 in) (0.036 Lead size (typ.) 0.50 × 0.50 mm (0.020 × 0.020 in.) (0.028 Dambar shear- 0.70 mm 0.99 m	nal Plated Through- Hole Diameter
off area (max.) (0.026 in) (0.036 Lead size (typ.) 0.50 × 0.50 mm (0.020 × 0.020 in.) 0.707 Dambar shear- 0.70 mm 0.99 m	
(0.020 × 0.020 in.) (0.028 Dambar shear- 0.70 mm 0.99 m	
off area (max.) (0.028 in) (0.039	nm 9 in)

Note: Refer to application note AN1027 for more information on soldering LED components.



OF PC BOARD

TOP SIDE OF
PC BOARD

CONVEYOR SPEED = 1.83 M/MIN (6 FT/MIN)□
PREHEAT SETTING = 150°C (100°C PCB)□
SOLDER WAVE TEMPERATURE = 245°C□
AIR KNIFE AIR TEMPERATURE = 390°C□
AIR KNIFE DISTANCE = 1.91 mm (0.25 IN.)□
AIR KNIFE ANGLE = 40°□
SOLDER: SN63; FLUX: RMA□

NOTE: ALLOW FOR BOARDS TO BE
SUFFICIENTLY COOLED BEFORE EXERTING MECHANICAL FORCE.

Figure 17. Recommended wave soldering profile

For product information and a complete list of distributors, please go to our website:

www.avagotech.com

